

# **Method of Forming a Dual Damascene Via by Using a Metal Hard Mask Layer**

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## **ABSTRACT OF THE INVENTION**

10 This invention relates to a method of forming a dual damascene  
via, in particular to a method of forming a dual damascene via by using a  
metal hard mask layer. The present invention uses a metal layer to be a  
hard mask layer to make the surface of the isolation layer become a level  
and smooth surface and not become a rounding convex and to prevent  
the via being connected with others vias to cause the leakage defects  
after forming the shape of the via.

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